

SC12793MP

**IN THE SPECIFICATION:**

Please replace paragraph [0020] with the following replacement paragraph:

**[0020]** FIG. 2 is a cross-sectional sectional view taken along line 2-2 of the substrate 10, which is along the wire 19. The integrated circuit 12 is attached to the substrate 10 with a die attach material 24. The die attach material 24 may be either an insulating material or conductive. If the vias under the integrated circuit ~~14~~ 12 are supplying a ground connection, there is a benefit for the die attach material 24 to be conductive. Conductive die attach material also may be useful for thermal conduction.